

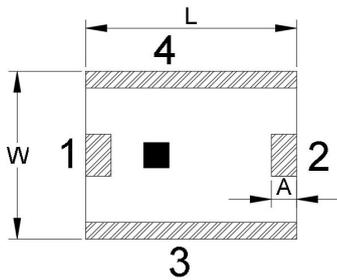
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

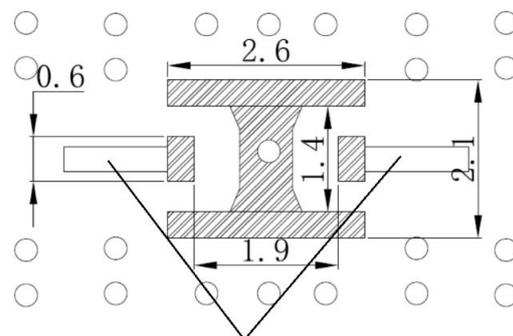
NO.	Parameter	SPC
1	Frequency (MHz)	5600~6000
2	Insertion Loss (dB)@5800MHz 25°C	≤3
	1dB Bandwidth (MHz)	≤700
3	3dB Bandwidth (MHz)	≤1000
4	VSWR(In BW)	≤2.0
5	Attenuation(dB)	≥50@4000MHz
		≥45@11200~12000MHz
6	In/Output Impedance (Ω)	50
Operating & Storage Condition (Component)		
Operation Temperature Range: -40°C ~ +85°C		
Storage Temperature Range: -40°C~ +85°C		
Storage Condition before Soldering (Included packaging material)		
Storage Temperature Range: +5 ~ +40 °C		
Humidity: 30 to 70% relative humidity		

Construction



PIN	Connection	PIN	Connection
1	Input port	3	GND
2	Output port	4	GND

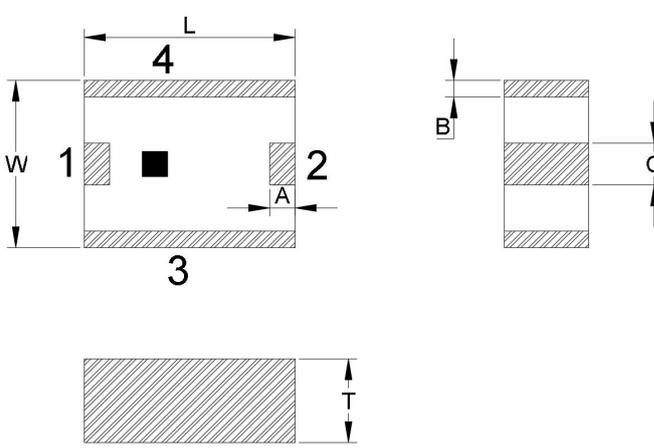
Mounting Considerations



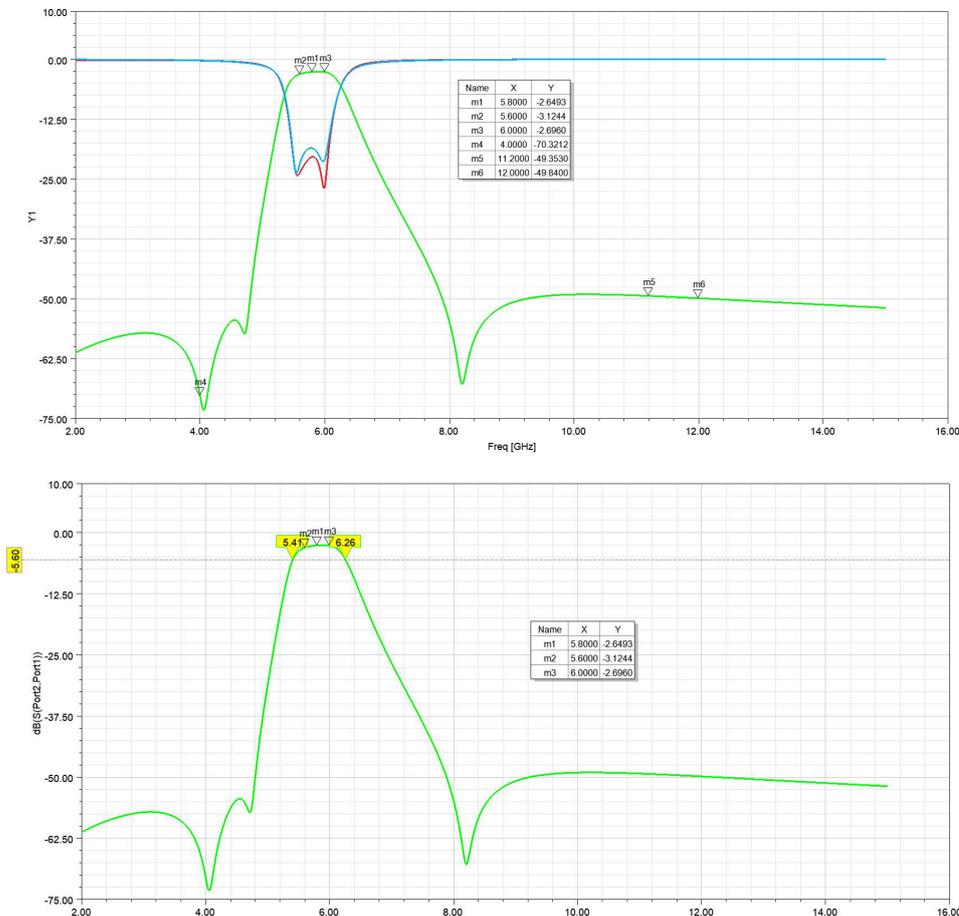
Line 50 Ω

Unit: mm

Dimensions

Figure	Symbol	Dimension (mm)
	L	2.50±0.20
	W	2.0±0.20
	T	1.0±0.20
	A	0.30±0.10
	B	0.20±0.10
	C	0.50±0.20

Typical Electrical Characteristics (T=25° C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.